





(0.40 mm) .0158"

SS4, ST4 SERIES

CRO BLADE & BEAM SOCKET & HEADER

SS4-20-3.00-L-D-K-TR

SS4 Mates with: **POSITIONS** LEAD **PLATING PER ROW STYLE OPTION** ST4 Mates with: **SPECIFICATIONS** (Required -3.00 in callout) = 3.00 mm For complete specifications (Required **–10, –20**, and recommended PCB layouts in callout) = 10 µ" (0.25 µm) see www.samtec.com?SS4 or -3.50 30, -40, -50 = Tape & www.samtec.com?ST4 Gold on contact, = 3.50 mm –K Reel Matte Tin on tail Insulator Material: = (3.50 mm) Black LCF .138" DIA Contact Material: No. of positions x Polyimide (0.40) .01575 + (3.54) .139Phosphor Bronze LEAD STYLE Plating: В Α Film Pick & Au or Sn over 50 μ" (1.27 μm) Ni Place Pad (2.85) (3.50)(4.35)3.00 .138 .112 **Current Rating:** .171 1.6 A per pin (3.35)(4.00)POWER/SIGNAL (2 pins powered) 132 APPLICATION Operating Temp Range: -55 °C to +125 °C RoHS Compliant: В **PROCESSING** → (0.40) .01575 (5.00)**→**|**←**(0.15) .006 Lead-Free Solderable: .197 SMT Lead Coplanarity: HIGH-SPEED CHANNEL PERFORMANCE (0.10 mm) .004" max SS4/ST4 @ 4 mm Mated Stack Height RECOGNITIONS Rating based on Samtec reference channel Compatible with For full SI performance data visit Samtec.com For complete scope of UMPT/UMPS for flexible or contact SIG@samtec.com recognitions see www.samtec.com/quality two-piece power/signal solutions **LEAD POSITIONS** PLATING D ${\sf TR}$ **PER ROW STYLE** OPTION **MATED HEIGHT** (Required -1.00in callout) = 1.00 mm (Required –10, –20, MATED in callout) = 10 µ" (0.25 µm) -1.50·30, –40, –50 =Tape & Gold on contact, = 1.50 mm -P Reel Matte Tin on tail = Pick & -2.50Place Pad **MATED HEIGHT*** = 2.50 mm SS4 LEAD STYLE

Some lengths, styles and options are non-standard, non-returnable.

-3.00

(4.00)

.157

(4.50)

(5.50)

.217

*Processing conditions will affect mated height.

-1.00

-1.50

-2.50

-3.50

(4.50)

.177

(5.00)

.197

(6.00)

.236

←(0.20) .008 → (0.40) .01575

No. of positions x

(0.40) .01575 + (1.58) .062



В

121

.141

180

(3.70)